

# Brazing explosively bonded Nb-Cu to Alumina Ceramic

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# **Outline – brazing explosively bonded Nb/Cu**

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- **Overview: Why this material set?**
  - **Switch processing methods:  
current, development, future**
- **Nb-  $\text{Al}_2\text{O}_3$  material properties**
- **Brazing experiments**
  - **Overview, processing, testing results**
- **Conclusions & path forward**

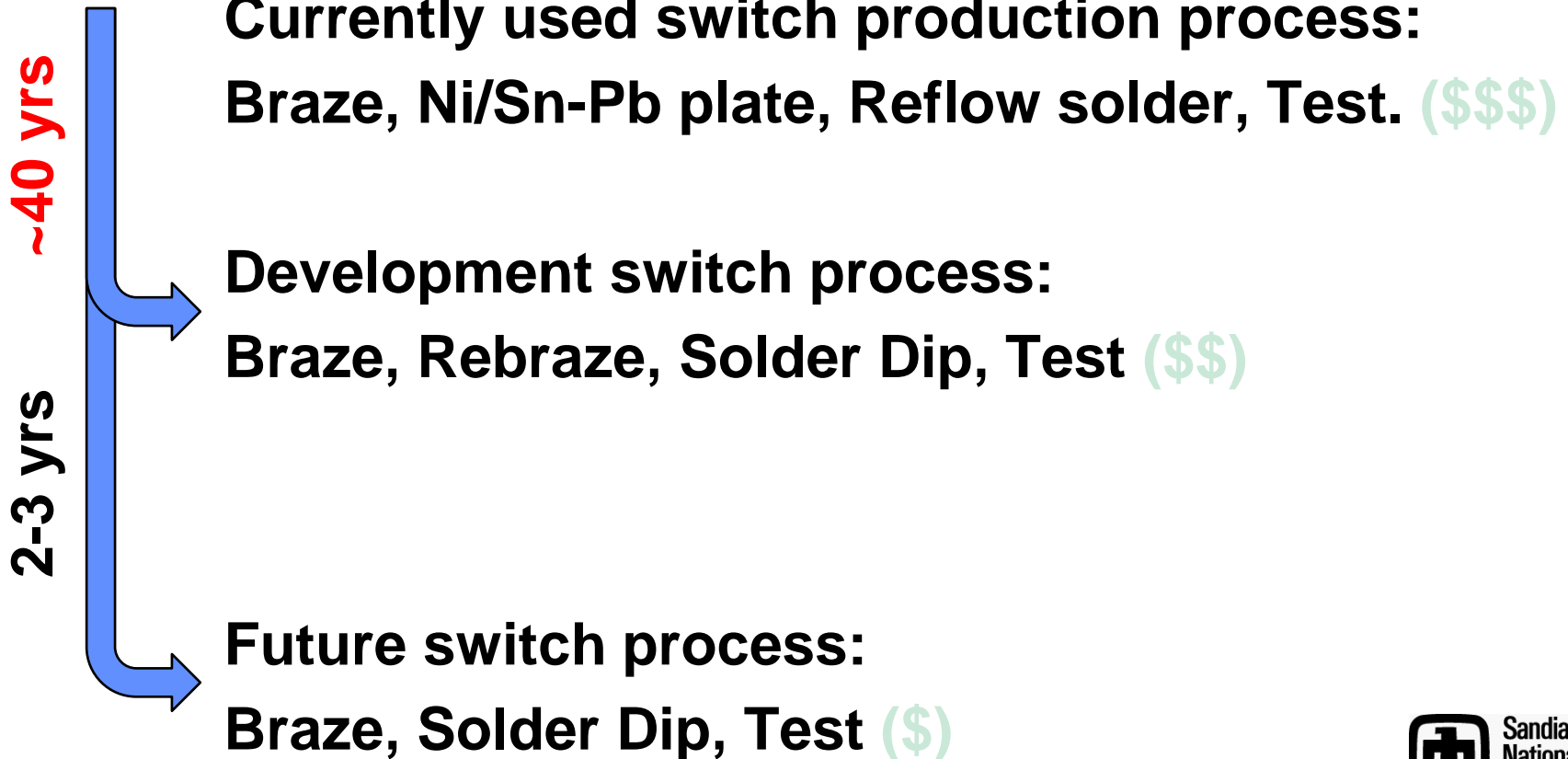


# Why the interest?

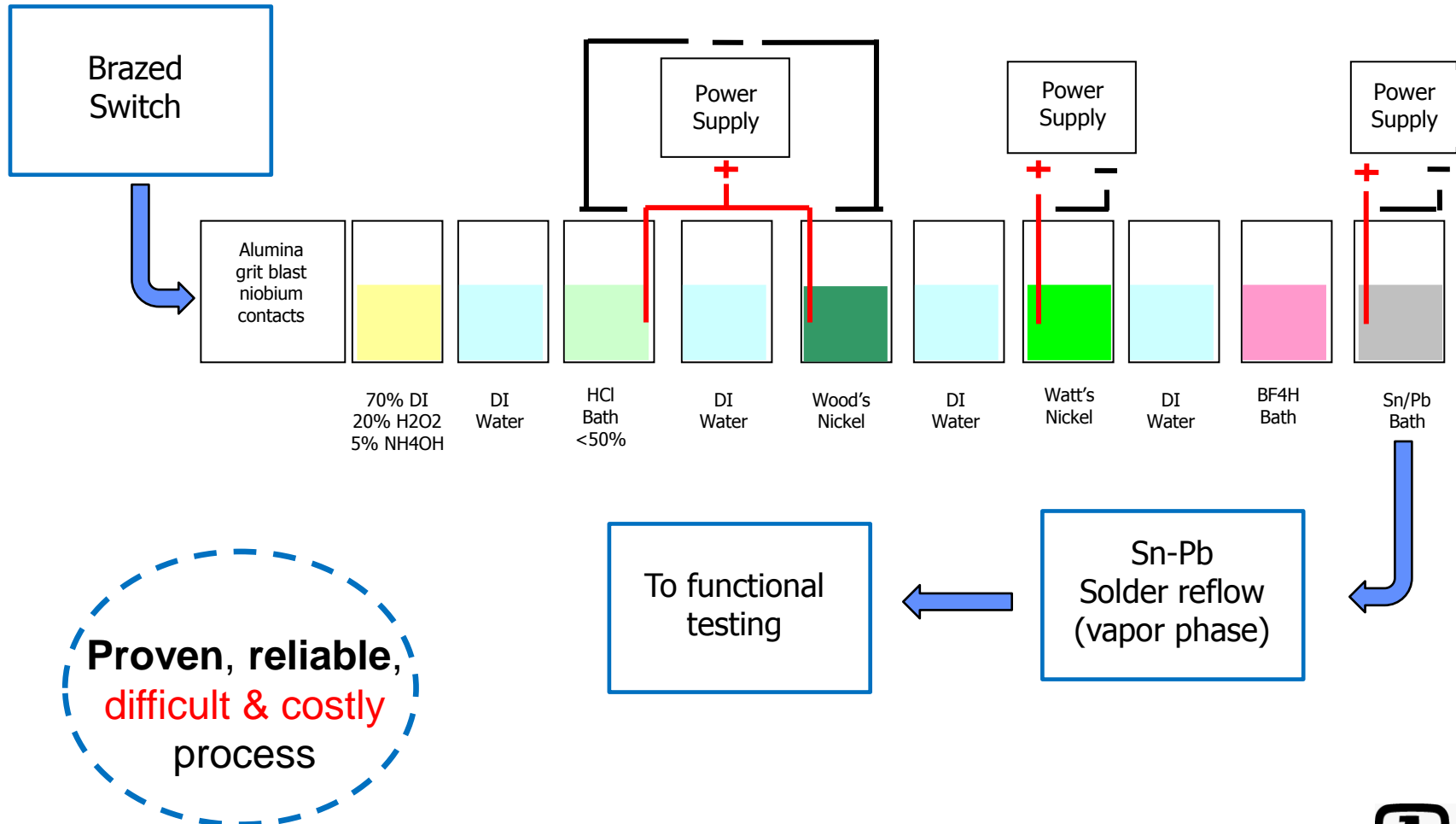
## Switch processing methods

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Why the interest?



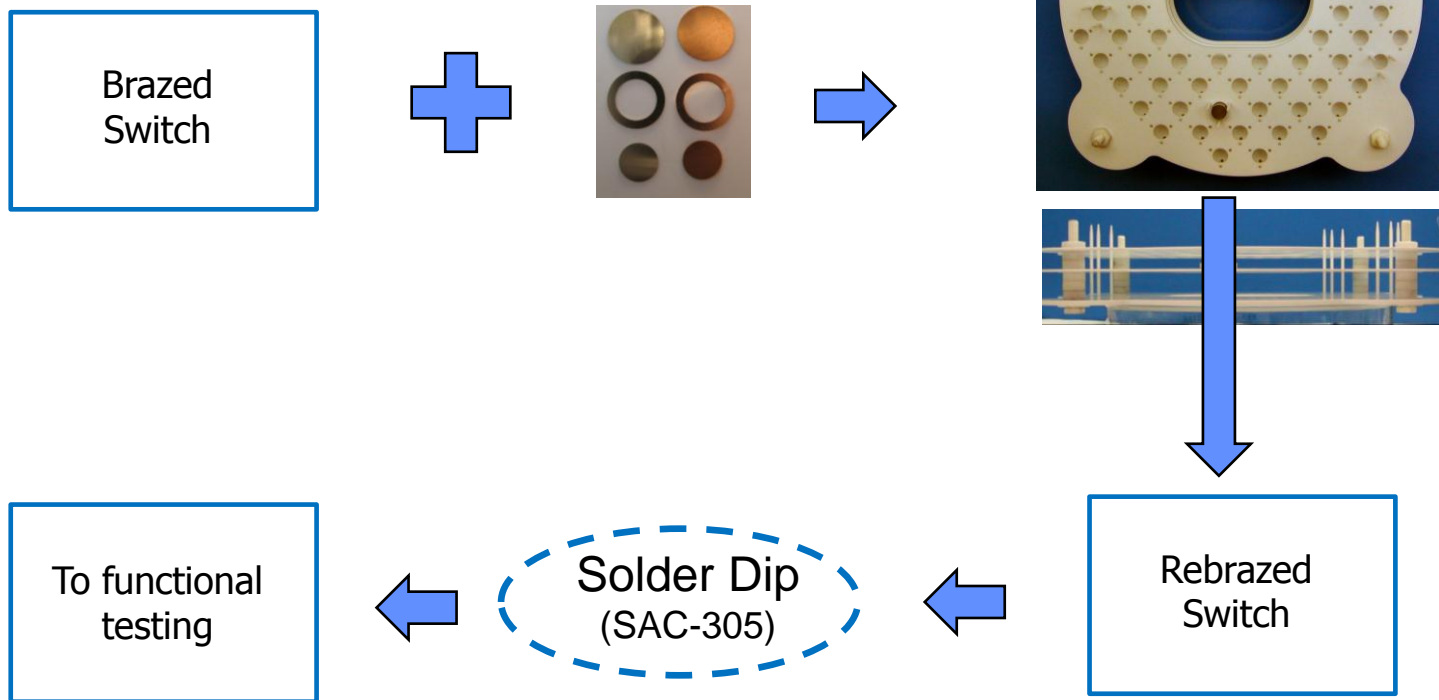
# Current production post-braze processing



# Development - step-brazing & solder dipping copper contacts

Refixture and furnace step-braze  
copper switch contacts

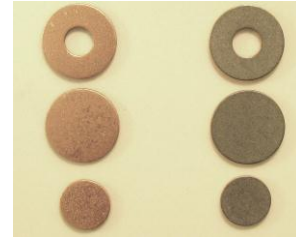
76 position laser-machined  $\text{Al}_2\text{O}_3$  fixture



# Future production: solder dipping explosively bonded Nb-Cu contacts



One fixturing step, one braze process



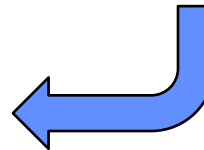
Explosively bonded Nb-Cu contacts



Solder Dip  
(SAC-305)

Successfully  
demonstrated  
Q3 2011!!

To functional  
testing



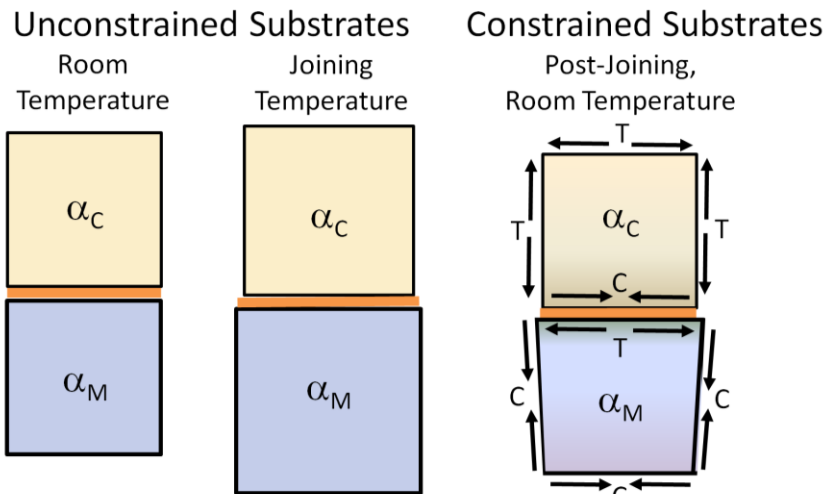


# Summary Table: three methods of switch fabrication

Switch fabrication method	Pros	Cons
Standard (Ni/Sn-Pb plate, reflow)	<ul style="list-style-type: none"><li>• 1-step brazing process</li><li>• Proven method</li><li>• Works well</li></ul>	<ul style="list-style-type: none"><li>• Expensive</li><li>• Time-consuming</li><li>• Complex plating process</li></ul>
2-Step braze method	<ul style="list-style-type: none"><li>• Eliminates plating/reflow</li><li>• Compatible with Pb-free solder-dipping processes</li><li>• Works well.</li></ul>	<ul style="list-style-type: none"><li>• Refixturing required</li><li>• 2-step brazing process</li><li>• Additional parts</li><li>• Additional risk</li></ul>
Braze using explosively bonded Nb-Cu	<ul style="list-style-type: none"><li>• 1-step brazing process</li><li>• Compatible with Pb-free solder-dipping processes</li><li>• Same part count as standard method.</li></ul>	<ul style="list-style-type: none"><li>• <b>Unproven method</b></li><li>• <b>CTE mismatch in bonded material</b></li><li>• <b>Unknown Nb-Cu bond interlayer strength</b></li><li>• <b>?</b></li></ul>

# Resultant stresses due to CTE mismatch

CTE Metal > CTE Ceramic, ( $\alpha_M > \alpha_C$ )



$\alpha_C$  = CTE Ceramic,  $\alpha_M$  = CTE Metal

T = Tension, C = Compression,

 = Ceramic Substrate

 = Metal Substrate

 = Braze Filler Metal

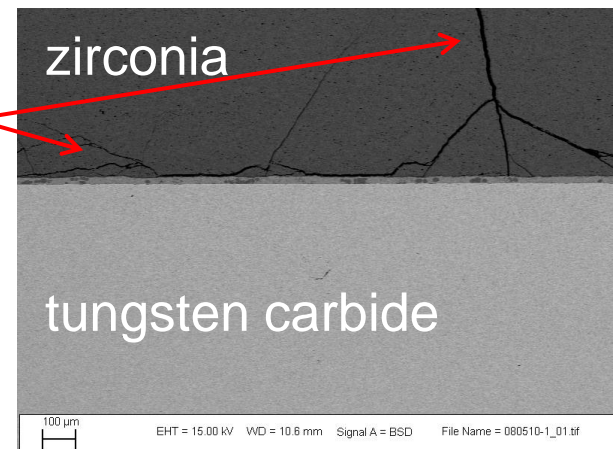
 = Stress Direction

Resultant stresses when brazing dissimilar materials

Sometimes the metal deforms



Sometimes the nonmetal fails





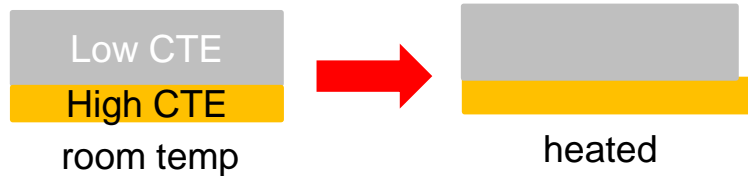


# Selected substrate and brazing filler metal material properties

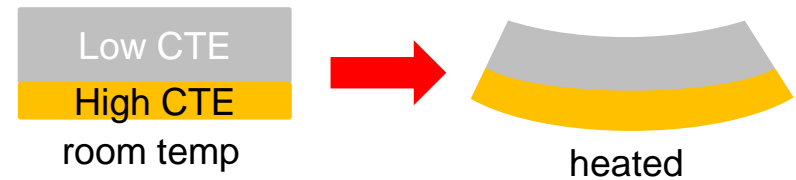
Material	Coefficient of Thermal Expansion (linear, 20-1000°C, *10 <sup>-6</sup> /°C)	Ultimate Tensile Strength / Elongation at Break	Compressive Strength
94% Al <sub>2</sub> O <sub>3</sub>	7.4	138 MPa (20 ksi)	1931 MPa (280 ksi)
Sapphire	6.7	400 MPa (58 ksi)	2930 MPa (425 ksi)
Niobium (commercially pure)	8.4	300 MPa (43.5 ksi)/30%	----
Kovar	11.3	517 MPa (75 ksi)/30%	----
Copper	25	210 MPa (31 ksi)/60%	----
BAu-3 (Nicoro™)	17.8	427 MPa (62 ksi)/28%	----
Nicoro™+2%Ti	17.8 (est.)	427 MPa (62 ksi)/28% (est.)	----

# Bi-metallic strip behavior

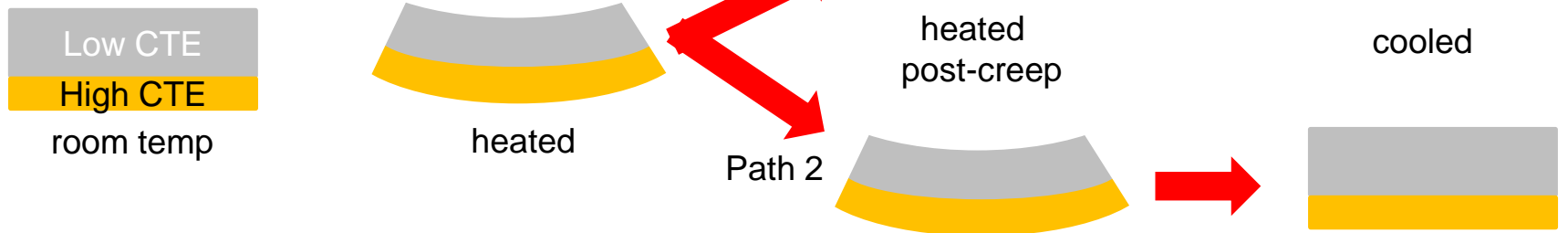
## Typical behavior *unconstrained*



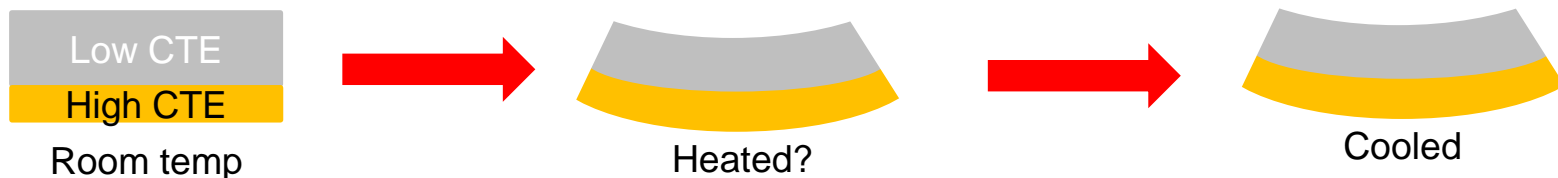
## Typical behavior *constrained*



## Expected Behavior

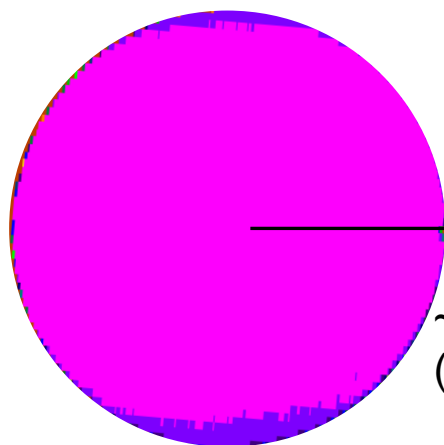


## Observed Behavior

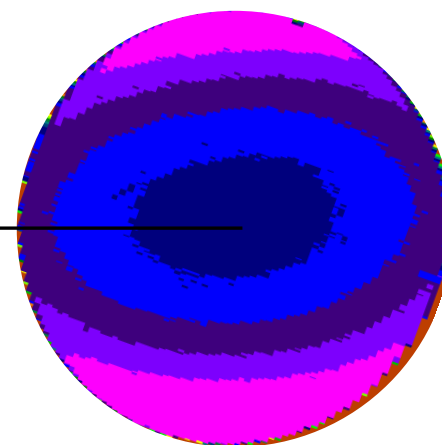


# Measured warp: 7.92mm diameter Nb disc #A1

As-Received

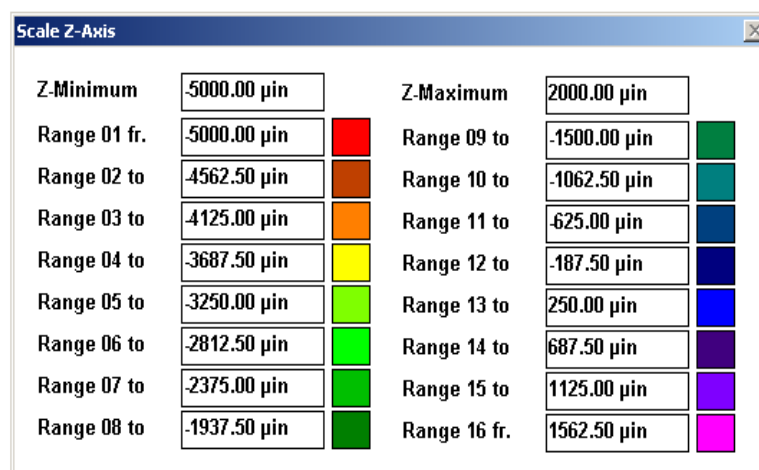
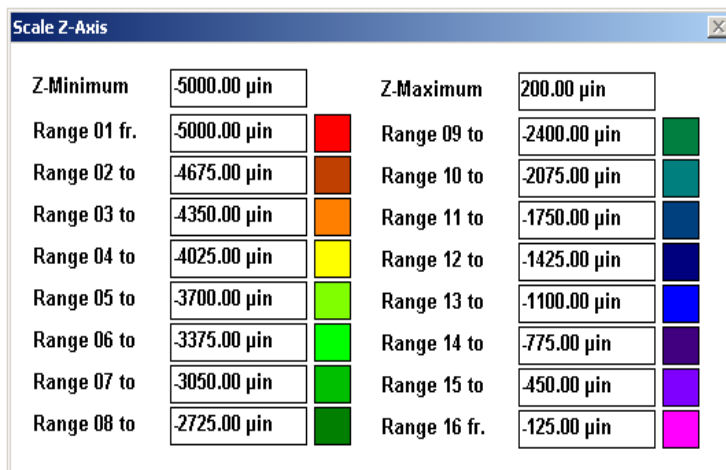


Post-Clean & Vac Bake



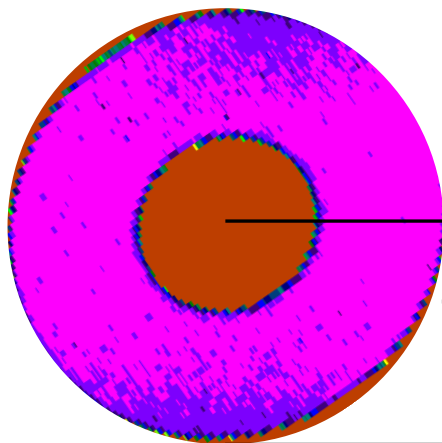
~0.000325"  
(0.0083mm)

~0.00175"  
0.0445mm

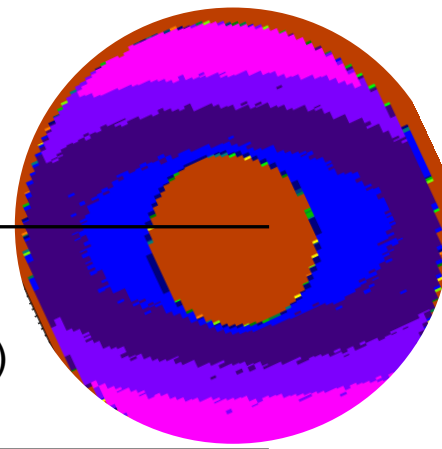


# Measured warp: 7.92mm OD x 3.10mm ID Nb washer #B2

As-Received



Post-Clean & Vac Bake



↑  
~0.000137"  
(0.0035mm)  
↓

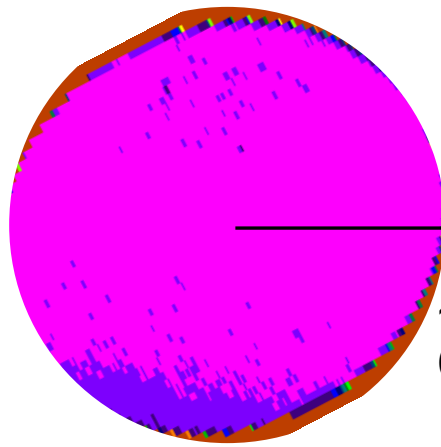
↑  
~0.00187"  
(0.0475mm)  
↓

Scale Z-Axis			
Z-Minimum	-2000.00 $\mu$ in	Z-Maximum	200.00 $\mu$ in
Range 01 fr.	-2000.00 $\mu$ in	Range 09 to	-900.00 $\mu$ in
Range 02 to	-1862.50 $\mu$ in	Range 10 to	-762.50 $\mu$ in
Range 03 to	-1725.00 $\mu$ in	Range 11 to	-625.00 $\mu$ in
Range 04 to	-1587.50 $\mu$ in	Range 12 to	-487.50 $\mu$ in
Range 05 to	-1450.00 $\mu$ in	Range 13 to	-350.00 $\mu$ in
Range 06 to	-1312.50 $\mu$ in	Range 14 to	-212.50 $\mu$ in
Range 07 to	-1175.00 $\mu$ in	Range 15 to	-75.00 $\mu$ in
Range 08 to	-1037.50 $\mu$ in	Range 16 fr.	62.50 $\mu$ in

Scale Z-Axis			
Z-Minimum	-8000.00 $\mu$ in	Z-Maximum	2000.00 $\mu$ in
Range 01 fr.	-8000.00 $\mu$ in	Range 09 to	-3000.00 $\mu$ in
Range 02 to	-7375.00 $\mu$ in	Range 10 to	-2375.00 $\mu$ in
Range 03 to	-6750.00 $\mu$ in	Range 11 to	-1750.00 $\mu$ in
Range 04 to	-6125.00 $\mu$ in	Range 12 to	-1125.00 $\mu$ in
Range 05 to	-5500.00 $\mu$ in	Range 13 to	-500.00 $\mu$ in
Range 06 to	-4875.00 $\mu$ in	Range 14 to	125.00 $\mu$ in
Range 07 to	-4250.00 $\mu$ in	Range 15 to	750.00 $\mu$ in
Range 08 to	-3625.00 $\mu$ in	Range 16 fr.	1375.00 $\mu$ in

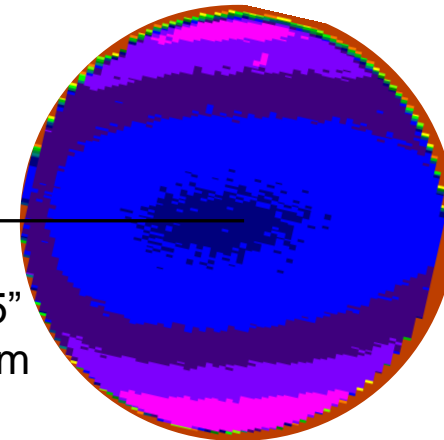
# Measured warp: 5.44mm diameter Nb disc – #C4

As-Received



~0.000136"  
0.0035mm

Post-Clean & Vac Bake



~0.00175"  
0.0445mm

Scale Z-Axis			
Z-Minimum	-2000.00 pin	Z-Maximum	180.00 pin
Range 01 fr.	-2000.00 pin	Range 09 to	-910.00 pin
Range 02 to	-1863.75 pin	Range 10 to	-773.75 pin
Range 03 to	-1727.50 pin	Range 11 to	-637.50 pin
Range 04 to	-1591.25 pin	Range 12 to	-501.25 pin
Range 05 to	-1455.00 pin	Range 13 to	-365.00 pin
Range 06 to	-1318.75 pin	Range 14 to	-228.75 pin
Range 07 to	-1182.50 pin	Range 15 to	-92.50 pin
Range 08 to	-1046.25 pin	Range 16 fr.	43.75 pin

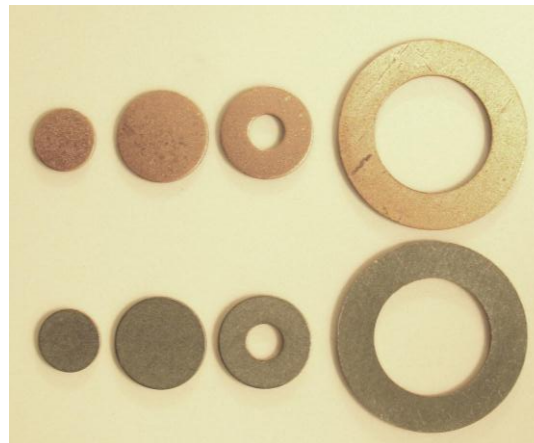
Scale Z-Axis			
Z-Minimum	-5000.00 pin	Z-Maximum	2000.00 pin
Range 01 fr.	-5000.00 pin	Range 09 to	-1500.00 pin
Range 02 to	-4562.50 pin	Range 10 to	-1062.50 pin
Range 03 to	-4125.00 pin	Range 11 to	-625.00 pin
Range 04 to	-3687.50 pin	Range 12 to	-187.50 pin
Range 05 to	-3250.00 pin	Range 13 to	250.00 pin
Range 06 to	-2812.50 pin	Range 14 to	687.50 pin
Range 07 to	-2375.00 pin	Range 15 to	1125.00 pin
Range 08 to	-1937.50 pin	Range 16 fr.	1562.50 pin

# Thermal-cycled Nb-Cu substrate behavior

Item	OD	Pre-bake flatness	Post-bake flatness	Average difference	Std. Dev
Small contact (disc)	5.44 mm 0.214"	0.010 mm 0.0004"	0.046 mm 0.0018"	<b>0.036 mm</b> <b>0.0014"</b>	0.010 mm 0.0004"
Medium contact (washer)	7.92 mm 0.312"	0.020 mm 0.0008"	0.056 mm 0.0022"	<b>0.036 mm</b> <b>0.0014"</b>	0.015 mm 0.0006"
Medium contact (disc)	7.92 mm 0.312"	0.015 mm 0.0006"	0.043 mm 0.0017"	<b>0.028 mm</b> <b>0.0011"</b>	0.013 mm 0.0005"
Tensile button interlayer (washer)	15.88 mm 0.625"	N/A	N/A	<b>~0.25 mm</b> <b>0.010"</b>	N/A

**Braze joint area comparison:**

**Switch contacts to tensile button interlayers**



# Active-brazing explosively bonded Nb-Cu to alumina

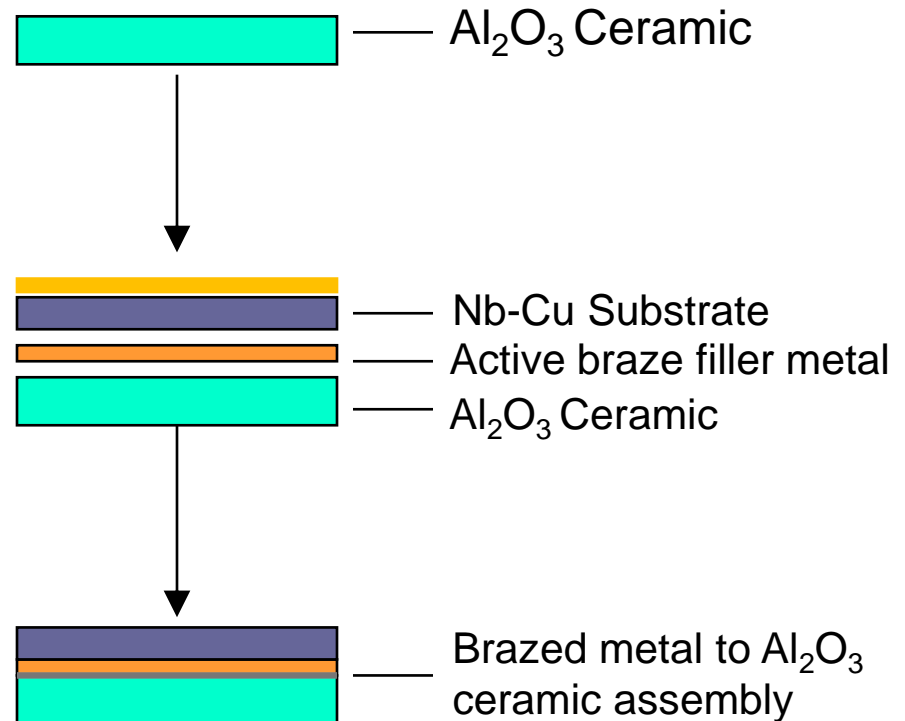
## Advantages

- Ease of use
- Variety of filler metal schemes & temperature ranges
- No specialized metallization equipment or processes required
- Easily brazed using standard filler metals

## Disadvantages

- Requires specialized equipment/atmosphere control
- Not usable with all joint designs
- Size constraints

## Active filler-metal brazing





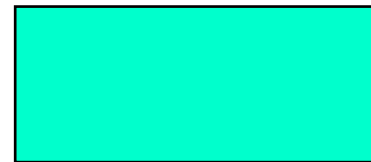
# Proposed tensile button experiment

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- **Fabricate ASTM-F19 tensile button assemblies using bare 94% and 96% alumina with explosively bonded niobium-copper interlayers.**
  - Alumina substrates air-fired @ 1575°C-2 hours, Nb-Cu interlayers vac-baked @ 1060°C-10 minutes, followed by 800°C-2 hours, flattened.
  - Braze filler metal, Nicoro+2%Ti, BAu-3 (other filler metals in process)
- **Input variables:**
  - **Bare alumina composition (94%, 96%),** surface finish varied from (28µin – 60µin)
    - Peak soak temp. (1025°C or 1030°C)
    - Peak soak time (1 or 2 minutes)
  - **Control samples (metallized, Mo-Mn/Ni plated 94% alumina tensile buttons)**
    - Peak soak temp. (1035°C or 1055°C)
    - Peak soak time (1 minute)
- **Response variables:** tensile strength & hermeticity



# ASTM-F19 tensile button geometry



← Bare  $\text{Al}_2\text{O}_3$



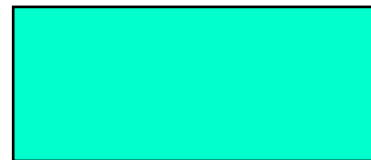
← “Active” BFM



← Nb - OFHC Cu



← “Active” BFM



← Bare  $\text{Al}_2\text{O}_3$

## Measured Responses

**Tensile strength:** MTS crosshead speed =  $8.38\text{E-}03$  mm/sec

**Hermeticity :** helium leak rates  $<5\text{E-}12$  atm-cc/sec desired



# Experiment drivers / goals

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1. Accommodate design changes in future products with no loss in hermeticity or joint tensile strength.
2. Use slightly lower active brazing process temperatures to minimize excess flow of braze filler metal sometimes observed using the current brazing profile.

$T_{\ell}$  Nicoro+2%Ti ~ 1020°C,  $T_{\ell}$  Nicoro ~ 1030°C

## Item

## Existing

## Proposed

**Contact Material:**

**Pure Niobium**

**Nb-Cu**

**$T_{\text{PEAK}}$ , Nicoro+2%Ti**

**1035°C – 1040°C**

**1025°C-1030°C**

**$T_{\text{PEAK}}$ , Nicoro**

**1060°C**

**1035°C-1055°C**



# Experimental trials

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- 36 tensile buttons were made in 6 separate brazing cycles.
  - 6 samples per condition.
  - Tensile strengths are the *average* of 6 samples.
- All samples were made in a modified Brew furnace in UHV atmosphere,  $1.3 \times 10^{-3}$  Pa ( $1 \times 10^{-6}$  Torr) at peak temperature. Braze joint preload was  $47 \text{ g/cm}^2$  ( $\sim 300 \text{ g/in}^2$ )
- Brazing Cycle:
  - $15^\circ\text{C/min}$  to  $975^\circ\text{C}$ , soak 10 minutes;
  - $10^\circ\text{C/min}$  to  $T_{\text{PEAK}}^*$ , soak  $t_{\text{PEAK}}^{**}$  minutes;
  - $25^\circ\text{C/min}$  to  $975^\circ\text{C}$ , soak 0 minutes;
  - $15^\circ\text{C/min}$  to ambient.

\*  $T_{\text{PEAK}} = 1025^\circ\text{C}, 1030^\circ\text{C}, 1035^\circ\text{C}$  or  $1055^\circ\text{C}$ ; \*\*  $t_{\text{PEAK}} = 1$  or 2 minutes



# Experimental trials – sample results

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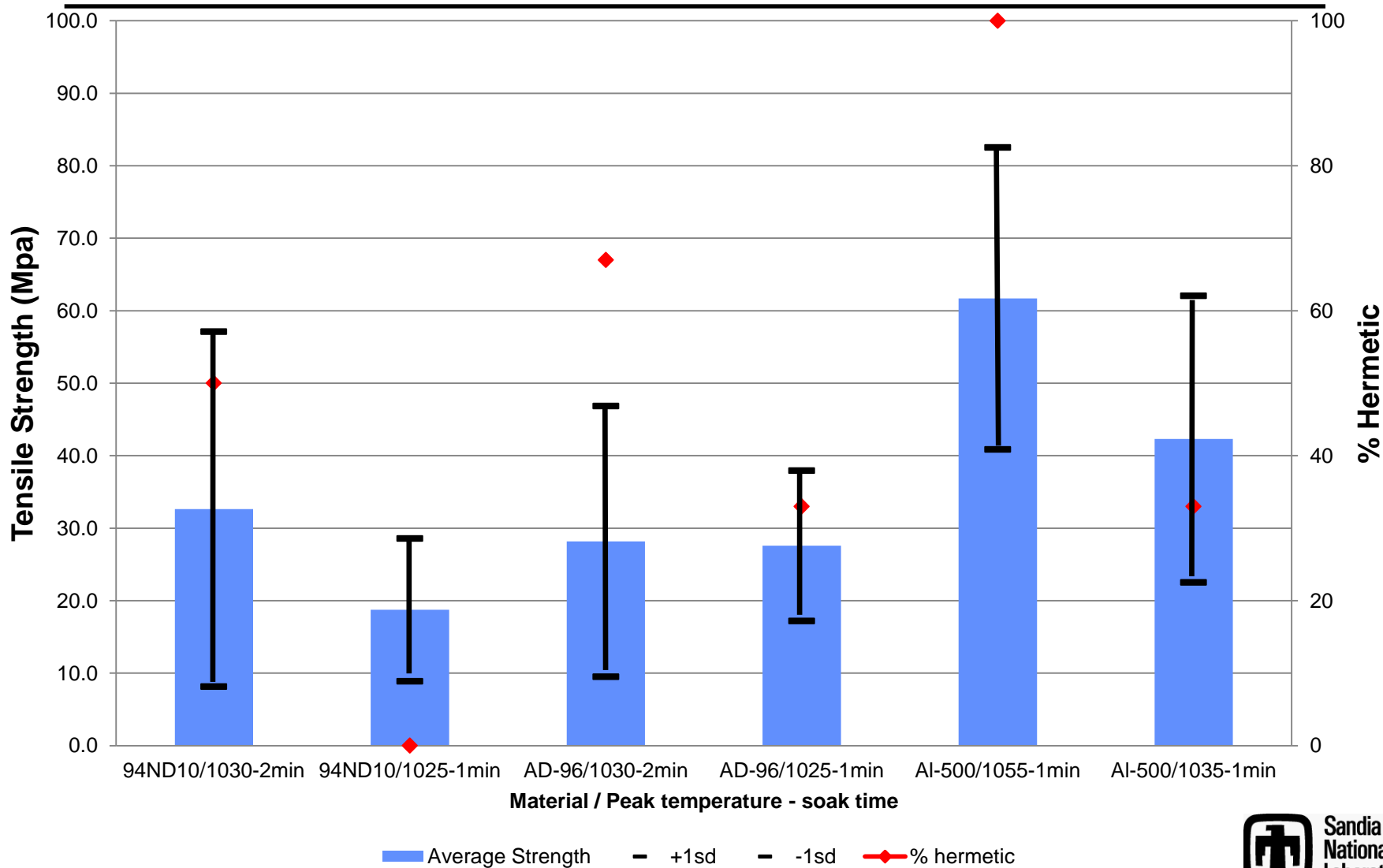
Ceramic Substrate	Peak Temp	Peak Time	Helium Leak Test Results (Ratio Passing*/Total)	Avg. Tensile Strength (psi)
94% alumina	1030°C	2 min.	3 / 6	34.2 ± 24.5 Mpa (4732)
94% alumina	1025°C	1 min.	0 / 6	18.7 ± 9.8 MPa (2717)
96% alumina	1030°C	2 min.	4 / 6	28.2 ± 18.7 MPa (4088)
96% alumina	1025°C	1 min.	2 / 6	27.6 ± 10.4 MPa (4000)
95% alumina metallized	1055°C	1 min.	6 / 6	61.7 ± 20.8 MPa (8947)
95% alumina metallized	1035°C	1 min.	2 / 6	42.3 ± 19.8 MPa (6135)

\*Passing = leak rates  $\leq 5.0\text{E-}012$  atm-cc/sec or NDL.

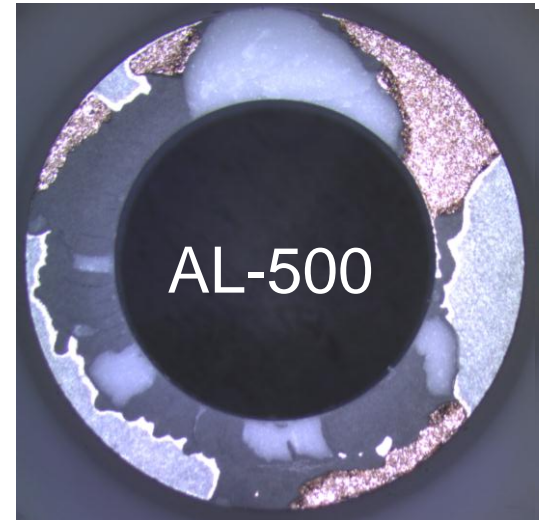
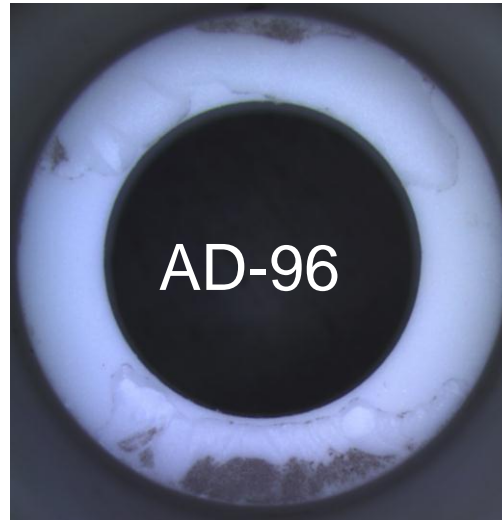
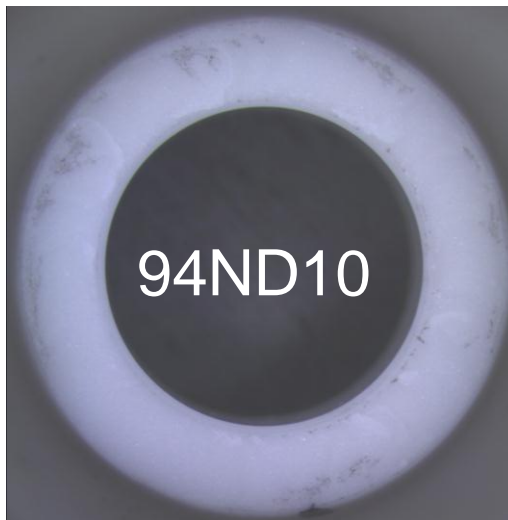
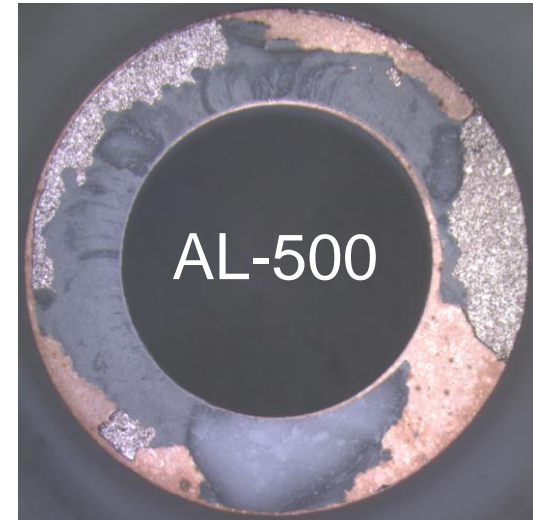
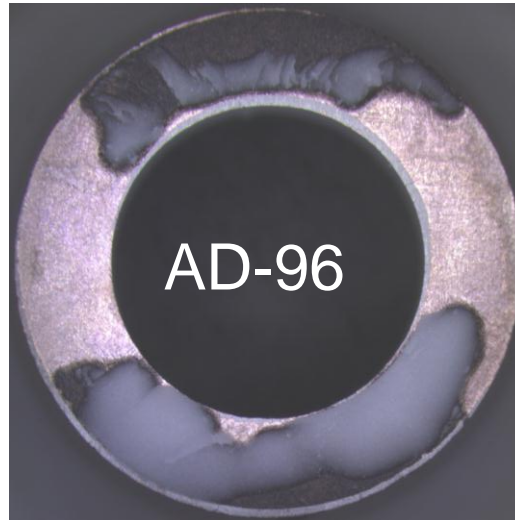
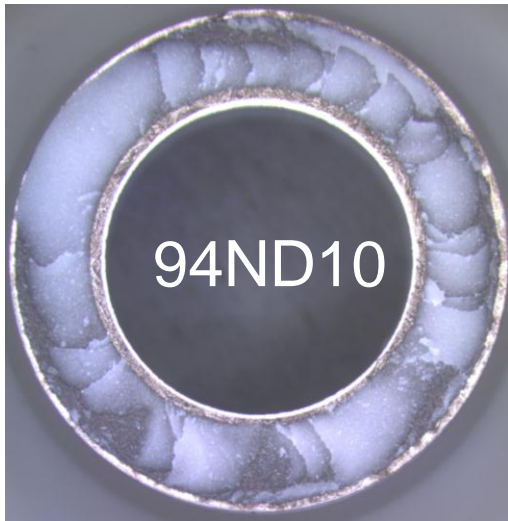


# Brazed Tensile Strength ASTM-F19 Tensile Buttons with explosively bonded Nb-Cu interlayers

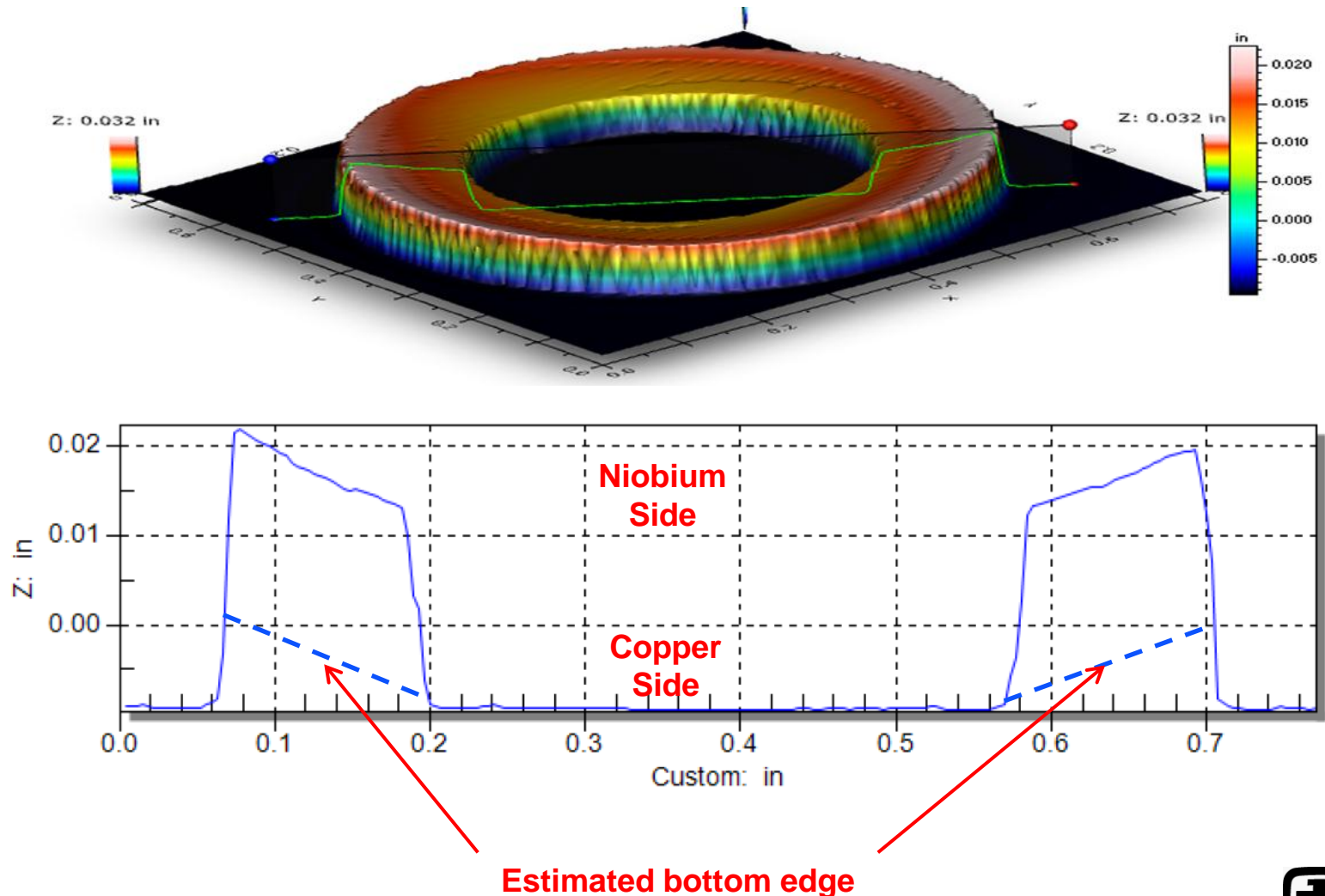
★ 120 MPa



# Observed brazed joint failures



# Measured Nb-Cu interlayer flatness following thermal cycle







# Proposed “cupping” mechanism

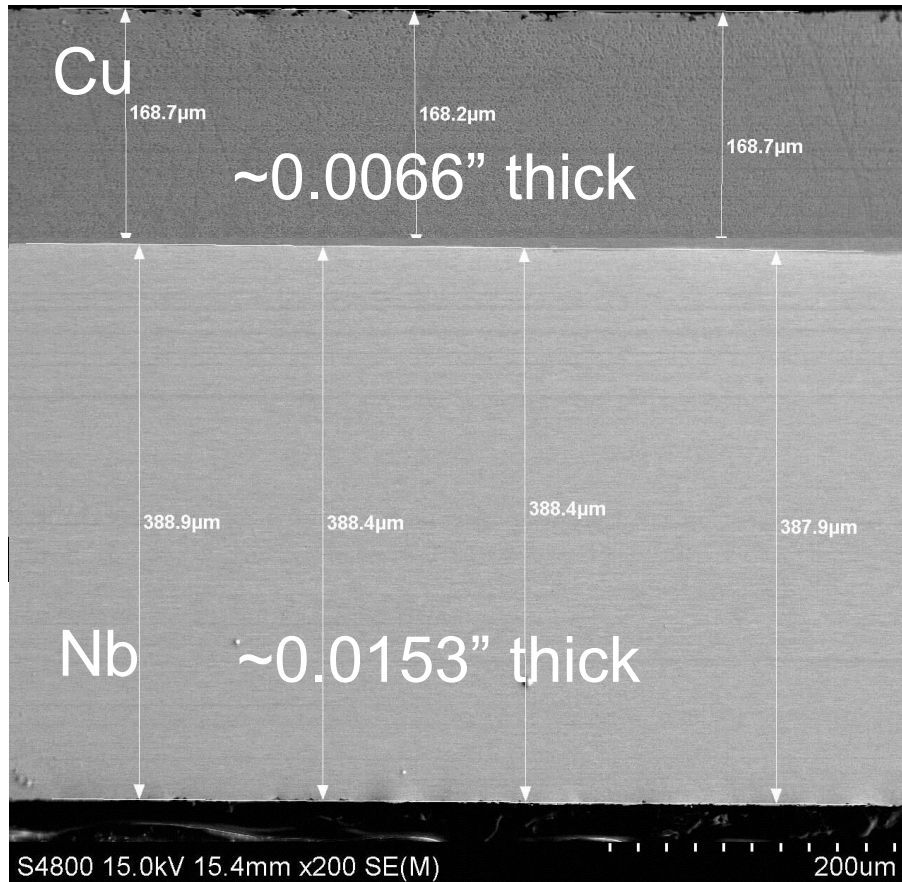
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## Niobium & Copper Selected Material Properties

	Niobium, Cold- worked	Niobium, Annealed	Copper, Cold-worked	Copper, Annealed
UTS (MPa/ksi) <sup>1</sup> = 1000°C, <sup>2</sup> = 600°C	600 / 87.0	300 / 43.5 90-120 / 13-17 <sup>1</sup>	344 / 49.9	210 / 30.5 10 / 1.5 <sup>2</sup>
CTE , linear 0-1000°C (in/in-°C)	8.5	8.5	24.8	24.8
Melting Pt. (°C)	2468	2468	1084	1084
Anneal Temp* (°C) *1/2 – 1/3 Abs mp (K)	1100 - 1550	1100 - 1550	400 - 630	400 - 630



# Cupping mechanism - continued



Cold-worked (high stress)  
Nb-Cu substrate at room  
temperature

Low CTE

High CTE

1060°C-10 minutes,  
800°C – 180 minutes

Nb warps as some internal  
stresses are relieved.

The much weaker Cu yields to the  
thicker, stronger Nb material.

Though under compression,  
Nb remains too strong to be  
deformed by the annealed  
Cu...cup shape remains.

Heated

Cooled



# Experimental trials (round 2)

## – additional joint preload sample results

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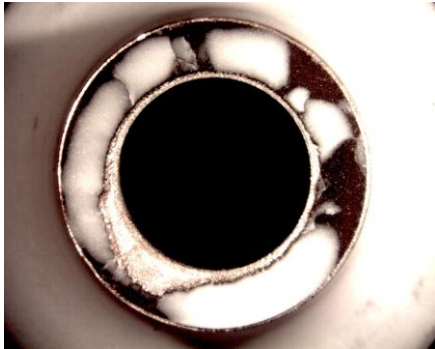
Ceramic Substrate	Peak Temp	Peak Time	Joint Preload (g/in <sup>2</sup> )	Helium Leak Test Results (Ratio Passing*/Total)	Tensile Strength (psi)
96% alumina	1055 <sup>o</sup> C	2 min.	101 g/cm <sup>2</sup> (653)	0/1	34.2 Mpa (4961)
96% alumina	1055 <sup>o</sup> C	2 min.	188 g/cm <sup>2</sup> (1212)	1/1	85.8 MPa (12447)
96% alumina	1050 <sup>o</sup> C	2 min.	275 g/cm <sup>2</sup> (1771)	1/1	52.3 MPa (7581)
96% alumina	1055 <sup>o</sup> C	2 min.	361 g/cm <sup>2</sup> (2329)	1/1	117.1 MPa (16989) Expected with this material set

\*Passing = leak rates  $\leq 5.0\text{E-}012$  atm-cc/sec or NDL.

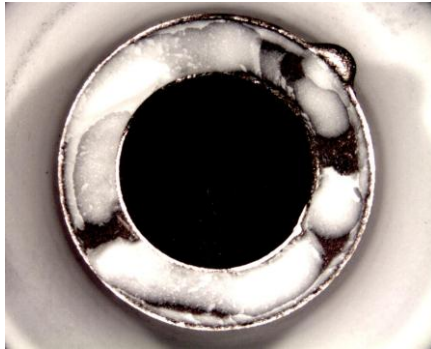
# Increased joint preload failure images

Increasing joint preload = increased tensile strength

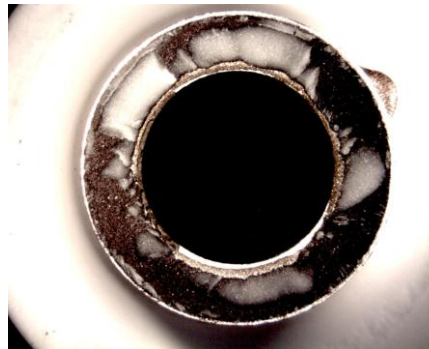
AD-96  
101 g/cm<sup>2</sup>  
34.2 Mpa / 4961 psi



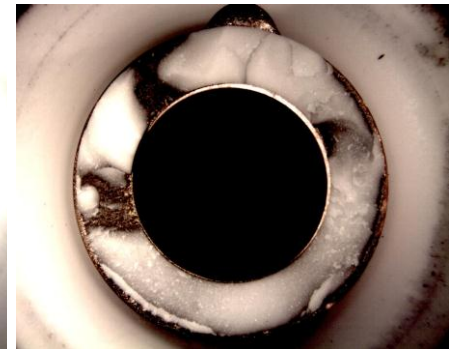
AD-96  
188 g/cm<sup>2</sup>  
85.8 Mpa / 12447 psi



AD-96  
275 g/cm<sup>2</sup>  
52.3 Mpa / 7581 psi



AD-96  
361 g/cm<sup>2</sup>  
117.1 Mpa / 16989 psi





# Conclusion & path forward

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## Conclusion

Residual stress in the explosively bonded Nb-Cu substrates is relieved during heating cycle resulting in excessive warp.

Additional joint preload to increase effective joint area greatly increases sample tensile strength.

Mass required to completely “flatten” substrates not practical for brazing manufacturing process.

Fully functional switches have been brazed/solder-dipped (SAC- 305 ) using the smaller bonded substrates.

## Path forward

Investigate alternative manufacturing methods

- Diffusion-bonding
- Cold-spraying
- Rolling/forming operation modifications

Perform additional characterization of braze joints.



# Acknowledgements

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- **Tom Crenshaw** – Mechanical properties testing
- **Randy Herrick** – SEM analysis
- **David Saiz** – OGP & measurements
- **Lynna Esquibel** – Measurements

(All Sandia National Laboratories, NM)



# The End

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*Thank you!*

**Questions?**